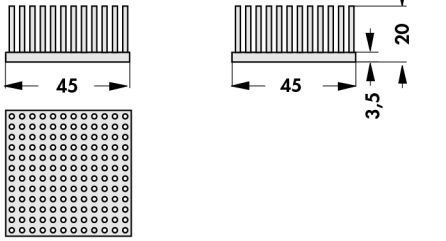
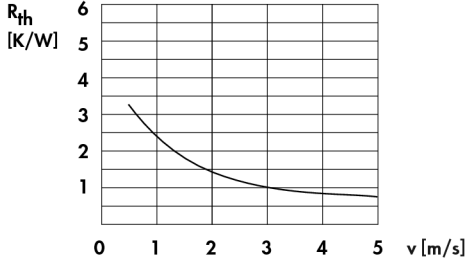
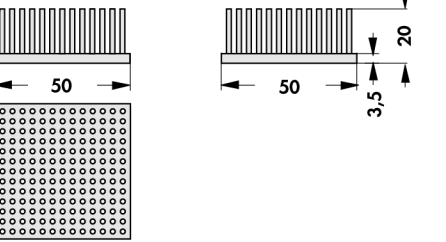
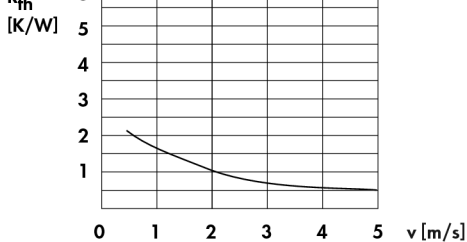
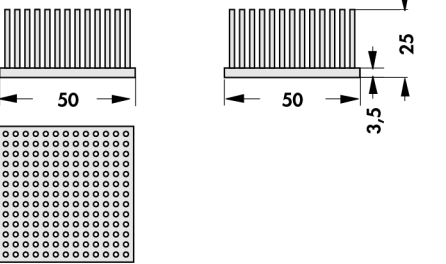
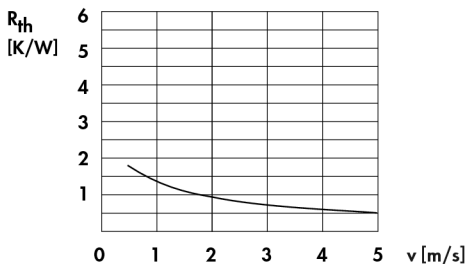
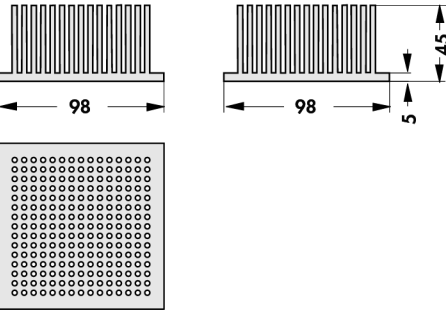
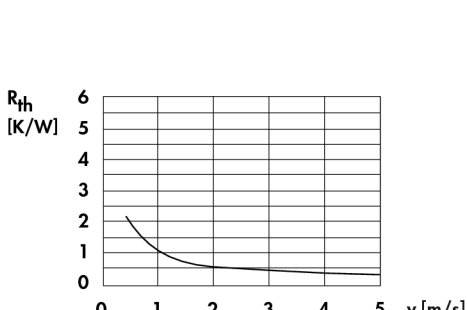


Pin heatsinks

<p>art. no.</p> <p>ICK S 45 x 45 x 20 WLF ... 45 x 45 weight: 36 g</p>		
<p>art. no.</p> <p>ICK S 50 x 50 x 20 WLF ... 50 x 50 weight: 43 g</p>		
<p>art. no.</p> <p>ICK S 50 x 50 x 25 WLF ... 50 x 50 weight: 49 g</p>		
<p>art. no.</p> <p>ICK S 98 x 98 x 45 WLF ... 98 x 98 weight: 301.3 g</p>		

Thermal conduct. foil WLF 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7

B 20

A

B

C

D

E

F

G

H

I

K

L

M

N